

6. (Currently Amended) An optical communications module according to claim 1, wherein said one or more dielectric wiring substrates comprise multilayer wiring substrates and an exposed surface of a grounding layer thereof has a metal plate adhered thereto, said metal plate being in thermal contact with the metal part of the chassis.

7. (Currently Amended) An optical communications module according to claim 1, wherein said dielectric wiring substrates comprise multilayer wiring substrates, and an grounding layer thereof has a heatsink provided on its exposed surface.

8. (Currently Amended) An optical communications module according to claim 1, wherein the metal part formed on one side of said one or more dielectric wiring substrates is partially removed, exposing terminals or other components of said optical transmitter section, optical receiver section, or optical transceiver section, through the removed portion to the outside of the optical communications module.

REMARKS

This Preliminary Amendment accompanies a request for continued examination (RCE).

In the final Office action (dated August 26, 2005) the claims were rejected as follows:

(1) Claims 1-8 were rejected as anticipated by U.S. Patent Publication No. 2002/0141706A1 (Nakura et al.).

As discussed below, applicant respectfully requests reconsideration.

The claims have been amended to recite one or more dielectric wiring substrates. According to particular examples in the specification, the dielectric wiring substrates can be either single-layer wiring substrates, or multiple-layer wiring substrates having a plurality of wiring layers laminated therein (page 6, lines 21-23). The dielectric wiring substrates may provide the photoelectric transfer function of the transmitter and receiver signals, the electrical signal processing capability, optical signal processing capability, and electrical/optical interface

capability in connection with an external circuit outside the optical communications module 1 (page 6, lines 16-20, pages 8-9). Thus, the dielectric wiring substrates include one or more wiring layers laminated therein on which optical parts are mounted.

The Nakura et al. reference does not disclose or suggest a dielectric wiring substrate. According to Nakura et al., the heatsink mechanism section (209) and housing main body section (207) form a connector housing (202) around a light-emitting and light-receiving element (203, 204) (page 5, paragraph 0093), but are not dielectric wiring substrates. Instead, the optical elements (203, 204) are mounted on a circuit board (216). Therefore, even if the heatsink (209) and housing main body section (207) were to be considered dielectric substrates, they neither include one or more wiring layers laminated therein nor have optical parts mounted thereon.

Furthermore, the dielectric wiring substrates of the present invention on which the optical elements are mounted are encased within the chassis. However, in Nakura et al. the optical elements are mounted on a circuit board (216) that is larger than the connector housing and, therefore, are not "encased" within the connector housing.

At least for the foregoing reasons, claim 1 is not anticipated and should be allowed. Claims 2-8 are not anticipated and should be allowed at least for the same reasons.

Furthermore, the dependent claims recite additional features that render those claims independently patentable. For example, claim 5 recites that the chassis has one or more vents. The final Office action alleges that the apparatus disclosed in Nakura et al. has a housing main body section with one or more openings that serve as vents (Figs. 4, 6). That is incorrect. The openings in the housing recesses (206) are for receiving an optical fiber. Although the embodiment of Figs. 4, 6 do not show the optical fiber, it is clear that the optical fiber would abut the opening (*See* Fig. 26 where the end face of optical fiber 450 abuts window section 411*h*). The presence of fiber optic connectors would prevent air from circulating in and out of the

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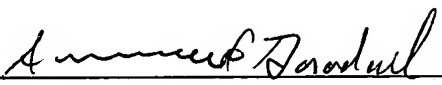
housing main body to improve heatsink efficiency. Therefore, the openings are not "vents" as recited in claim 5.

It is believed that all of the pending claims have been addressed. However, the absence of a reply to a specific rejection, issue or comment does not signify agreement with or concession to that rejection, issue or comment. In addition, because the arguments made above may not be exhaustive, there may be reasons for patentability of any or all pending claims (or other claims) that have not been expressed. Finally, nothing in this paper should be construed as an intent to concede any issue with regard to any claim, except as specifically stated in this paper, and the amendment of any claim does not necessarily signify concession of unpatentability of the claim prior to its amendment.

Please apply any charges or credits to deposit account 06-1050.

Respectfully submitted,

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